Special Issue

Advanced Memory Devices

Message from the Guest Editor

I would like to cordially invite you to contribute a paper to a Special Issue of the open access journal *Applied Sciences*, entitled “Advanced Memory Devices”, which aims to present recent developments of advanced memories with volatile and nonvolatile behaviors for applications in high-speed and low-power operation, high-density storage, biomedicine, Internet of Things (IoT), neural networks, artificial intelligence (AI), and so on. This Special Issue contains volatile memories (DRAM and SRAM) and nonvolatile memories (flash, RRAM, MRAM, PCM, FeRAM, etc.) with novel device strucutres, materials, and design for some specific applications. I invite you to submit your research on these topics, in the form of original research papers and articles. **Keywords:** volatile; nonvolatile; high-speed; low-power; high-density storage; biomedicine; Internet of Things (IoT); neural network; artificial intelligence (AI)

Guest Editor

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Deadline for manuscript submissions

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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